

--Currently, the pitch of contact pads 106, 108 on a CLGA package 100 is such that the spring clips 302-308 of the FIG. 3 socket 300 provide a means for grossly aligning a package's contact pads 106, 108 over a socket's elastomer buttons 402, 404. A mechanism for fine-tuning a package's alignment is therefore needed. Such an alignment mechanism is illustrated in FIG. 5. The alignment mechanism comprises a number of alignment pads 500, 502, 504 (at least two, and preferably three) which are applied to a package 100 at known locations (e.g., at corners) with respect to the package's pattern of contact pads 106, 108. Preferably, the alignment pads 500, 502, 504 are applied to the same surface as the pattern of contact pads 106, 108. The alignment pads 500, 502, 504 are also preferably applied to the package 100 at the same time that the pattern of contact pads 106, 108 is applied to the package 100. In this manner, their locations with respect to the package's contact pads 106, 108 can be more precisely controlled. For example, the alignment pads 500, 502, 504 may be applied at the same time that the contact pads 106, 108 are applied, by means of a silk screening, stenciling, or plating operation.--

Please rewrite the paragraph beginning on page 10, line 20, as follows:

--Each of the FIG. 5 alignment pads 500, 502, 504 may be used as a means for attaching (e.g., soldering) an alignment member to an integrated circuit package, as illustrated in FIGS. 7, 8, 11 & 14. A more detailed discussion of the means by which an alignment member may be attached to an alignment pad is found below. However, this discussion is preceded by a discussion of the types of alignment members which may be attached to an alignment pad.--

In the Claims:

Please cancel claims 3-6, 10, 12, 15, 19-25.

Please amend claims 1, 7-9, 11, 13, 16-18, 26 and 27 to read as follows: